2-178313-5 - ACTIVE

Dynamic Series | Dynamic 3000 Series

TE Internal #: 2-178313-5 PCB Mount Header, Vertical, Wire-to-Board, 3 Position, 3.81 mm [. 15 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, Dynamic 3000 Series

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles > Header Assembly: Wire-to-Board, 15A, gold or tin plated



Connector System: Wire-to-Board

Number of Positions: 3

Number of Rows: 1

Centerline (Pitch): 3.81 mm [.15 in]

PCB Mount Orientation: Vertical

All Header Assembly: Wire-to-Board, 15A, gold or tin plated (120)



Features

Product Type Features

Connector System	Wire-to-Board				
Header Type	Fully Shrouded				
Sealable	No				
Connector & Contact Terminates To	Printed Circuit Board				
PCB Connector Assembly Type	PCB Mount Header				
Configuration Features					
Number of Positions	3				
Number of Rows	1				
PCB Mount Orientation	Vertical				
Body Features					
Primary Product Color	Black				
Contact Features					

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Contact Mating Area Plating Material Thickness	2 µm[80 µin]
Contact Mating Area Plating Material Finish	Matte
Contact Mating Area Plating Material	Tin
Contact Type	Pin
Contact Current Rating (Max)	12 A
Termination Features	
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	With
PCB Mount Retention Type	Retention Leg
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	With
Housing Features	
Housing Material	Polyester GF
Centerline (Pitch)	3.81 mm[.15 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Power & Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Type	Box, Tube
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold

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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts



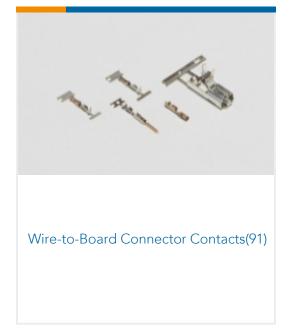
Also in the Series | Dynamic 3000 Series



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Customers Also Bought



TE Part #6469169-1 HMZD 2PR RA HDR 40P	TE Part #826470-8 2X8P MOD II SHROUDED HEADER, RT ANG.	TE Part #1241050-3 2x3P MOD II BREAK AWAY HDR,SMD, BLISTER	TE Part #2176329-3 CRGP 1210 15R 1%
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TE Part #1376133-2 DYNAMIC D-3500 HDR ASSY 4P	TE Part #1-1734839-8 FPC CONN. 0.5MM PITCH T/C,18P	TE Part #1649328-1 RTD14005	TE Part #2-2362375-4 PCIE GEN4, 164POS ,30u" ,DIP ,2.3 mm TAIL

Documents

Product Drawings DYNAMIC D3100 HDR V 3P ASSY English **CAD** Files 3D PDF Customer View Model ENG_CVM_CVM_2-178313-5_J.2d_dxf.zip

C For support call+1 800 522 6752

3D

PCB Mount Header, Vertical, Wire-to-Board, 3 Position, 3.81 mm [.15 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, Dynamic 3000 Series



English

Customer View Model ENG_CVM_CVM_2-178313-5_J.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-178313-5_J.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages 1-1773732-4_DYNAMIC_SERIES_CATALOG_ENGLISH

Japanese

1-1773732-4_DYNAMIC_SERIES_CATALOG_ENGLISH

English

Product Specifications

Product Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English

Agency Approvals TUV Certificate

English